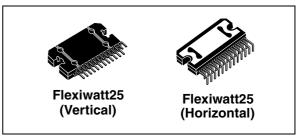


4 x 50W multifunction quad power amplifier with built-in diagnostics features

Features

- Multipower BCD technology
- MOSFET output power stage
- DMOS power output
- New Hi-efficiency (class SB)
- High output power capability 4x28W/4Ω @ 14.4V, 1KHZ, 10% THD, 4x50W max, power
- Max. output power 4x72W/2Ω
- Full I²C bus driving:
 - St-by
 - Independent front/rear soft play/mute
 - Selectable gain (for low noise line output function)
 - High efficiency enable/disable
 - I²C bus digital diagnostics (including AC and DC load detection)
- Full fault protection
- DC offset detection
- Four independent short circuit protection
- Clipping detector (2%/10%)
- Linear thermal shutdown with multiple thermal warning
- ESD protection



Description

The TDA7564B is a new BCD technology QUAD BRIDGE type of car radio amplifier in Flexiwatt25 package specially intended for car radio applications.

Thanks to the DMOS output stage the TDA7564B has a very low distortion allowing a clear powerful sound. Among the features, its superior efficiency performance coming from the internal exclusive structure, makes it the most suitable device to simplify the thermal management in high power sets.

The dissipated output power under average listening condition is in fact reduced up to 50% when compared to the level provided by conventional class AB solutions. This device is equipped with a full diagnostics array that communicates the status of each speaker through the I^2C bus.

Order codes

Part number	Package	Packing		
TDA7564B	Flexiwatt25 (vertical)	Tube		
TDA7564BH	Flexiwatt25 (horizontal)	Tube		

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1 Block diagrams and application circuit

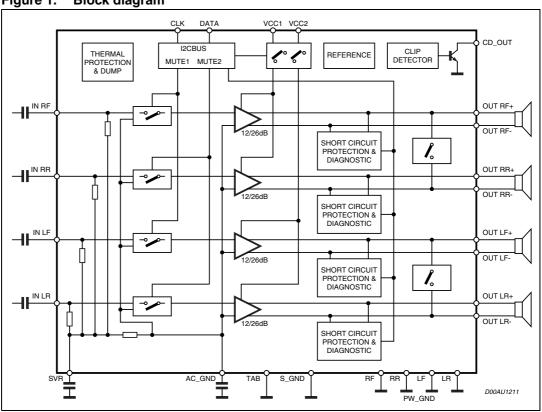
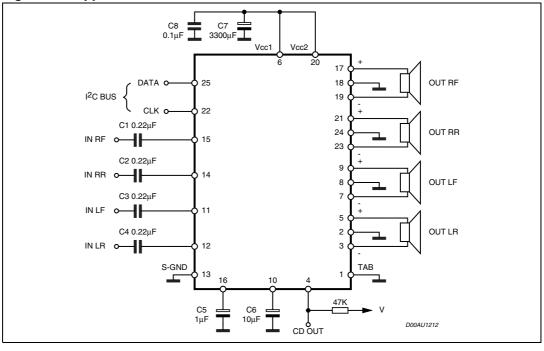




Figure 2. Application circuit



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2 Pins description

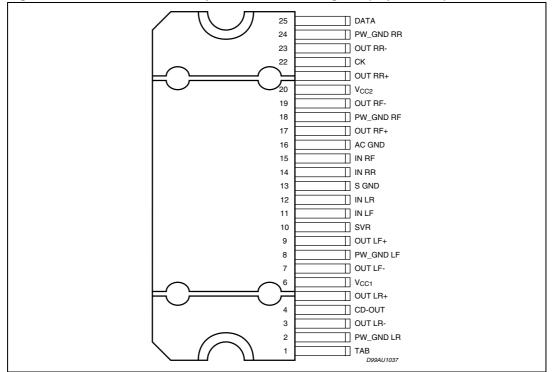
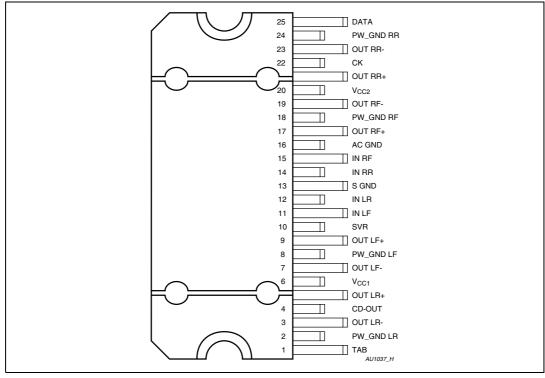


Figure 3. Flexiwatt25 vertical pins connection diagram (Top of view)

Figure 4. Flexiwatt25 horizontal pins connection diagram (Top of view)





3 Electrical specifications

3.1 Absolute maximum ratings

Table 1. Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{op}	Operating Supply Voltage	18	V
VS	DC Supply Voltage	28	V
V _{peak}	Peak Supply Voltage (for t = 50ms)	50	V
V _{CK}	CK pin Voltage	6	V
V _{DATA}	Data Pin Voltage	6	V
Ι _Ο	Output Peak Current (not repetitive t = 100ms)	8	Α
Ι _Ο	Output Peak Current (repetitive f > 10Hz)	6	Α
P _{tot}	Power Dissipation T _{case} = 70°C	85	W
T _{stg} , T _j	Storage and Junction Temperature	-55 to 150	°C

3.2 Thermal data

Table 2. Thermal Data

Symbol	Parameter	Value	Unit	
R _{th j-case}	Thermal Resistance Junction to case	Max.	1	°C/W

3.3 Electrical characteristics

Refer to the test circuit, $V_S = 14.4V$; $R_L = 4\Omega$; f = 1KHz; $G_V = 30dB$; $T_{amb} = 25^{\circ}C$; unless otherwise specified.

Table 3. Electrical Characteristics

Symbol	Parameter	Min.	Тур.	Max.	Unit				
POWER AMPLIFIER									
V _S	Supply Voltage Range		8		18	V			
I _d	Total Quiescent Drain Current			170	300	mA			
P _O	Output Dower	Max. power (V _S = 15.2V, square wave input (2Vrms))		50		W			
	Output Power	THD = 10% THD = 1%	25 20	28 22		W W			



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Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
P _O	Output Power	$\label{eq:RL} \begin{split} &R_{L}=2\Omega; \; EIAJ\; (V_{S}=13.7V) \\ &R_{L}=2\Omega; \; THD\; 10\% \\ &R_{L}=2\Omega; \; THD\; 1\% \\ &R_{L}=2\Omega; \; MAX\; POWER \end{split}$	55 40 32 60	68 50 40 75		W W W W
THD	Total Harmonic Distortion	$P_O = 1W$ to 10W; STD MODE HE MODE; $P_O = 1.5W$ HE MODE; $P_O = 8W$		0.02 0.015 0.15	0.1 0.1 0.5	% % %
		$G_V = 12$ dB; STD Mode $V_O = 0.1$ to 5VRMS		0.02	0.05	%
CT	Cross Talk	f = 1KHz to 10KHz, $R_g = 600\Omega$	50	60		dB
R _{IN}	Input Impedance		60	100	130	KΩ
G _{V1}	Voltage Gain 1		25	26	27	dB
ΔG_{V1}	Voltage Gain Match 1		-1		1	dB
G _{V2}	Voltage Gain 2		11	12	13	dB
ΔG_{V2}	Voltage Gain Match 2		-1		1	dB
E _{IN1}	Output Noise Voltage 1	$R_g = 600\Omega 20Hz$ to 22kHz		35	100	μV
E _{IN2}	Output Noise Voltage 2	$R_g = 600\Omega; GV = 12dB$ 20Hz to 22kHz		12	30	μV
SVR	Supply Voltage Rejection	f = 100Hz to 10kHz; V _r = 1Vpk; 50 60 $R_g = 600\Omega$		60		dB
BW	Power Bandwidth		100			KHz
A_{SB}	Stand-by Attenuation		90	110		dB
I _{SB}	Stand-by Current	V _{st-by} = 0		25	50	μA
A _M	Mute Attenuation		80	100		dB
V _{OS}	Offset Voltage	Mute & Play	-100	0	100	mV
V _{AM}	Min. Supply Mute Threshold		7	7.5	8	V
CMRR	Input CMRR	V_{CM} = 1Vpk-pk; Rg = 0 Ω		55		dB
T _{ON}	Turn ON Delay	D2/D1 (IB1) 0 to 1		20	40	ms
T _{OFF}	Turn OFF Delay	D2/D1 (IB1) 1 to 0		20	40	ms
CD _{LK}	Clip Det High Leakage Current	CD off		0	5	μA
CD _{SAT}	Clip Det Sat. Voltage	CD on; I _{CD} = 1mA		150	300	mV
CD	Clip Det THD level	D0 (IB1) = 1	5	10	15	%
CD _{THD}		D0 (IB1) = 0	1	2	3	%

 Table 3.
 Electrical Characteristics (continued)



Table 3.	Electrical Characteristics					
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
TURN ON	I DIAGNOSTICS 1 (Power Amplifi	ier Mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)				1.2	V
Pvs	Short to Vs det. (above this limit, the Output is considered in Short Circuit to ${\rm V}_{\rm S})$	hort Power Amplifier in st-by 1.8 1.8 1.8 1.8 1.7 er Mode) s d in Power Amplifier in st-by mit,	Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
Lsc	Shorted Load det.				0.5	Ω
Lop	Open Load det.		85			Ω
Lnop	Normal Load det.		1.75		45	Ω
TURN ON	I DIAGNOSTICS 2 (Line Driver Me	ode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in st-by			1.2	V
Pvs	Short to Vs det. (above this limit, the Output isconsidered in Short Circuit to VS)		Vs -1.2			V
Pnop	Normal operation thresholds.(Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
Lsc	Shorted Load det.				2	Ω
Lop	Open Load det.		330			Ω
Lnop	Normal Load det.		7		180	Ω
PERMAN	ENT DIAGNOSTICS 2 (Power Am	plifier Mode or Line Driver Mode	e)			
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)				1.2	V
Pvs	Short to Vs det. (above this limit, the Output is considered in Short Circuit to VS)	Power Amplifier in Mute or Play, one or more short circuits protection activated	Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
1	Shorted Load Det.	Pow. Amp. mode			0.5	Ω
L _{SC}	Shorleu Load Del.	Line Driver mode			2	Ω
V _O	Offset Detection	Power Amplifier in play, AC Input signals = 0	±1.5	±2	±2.5	V

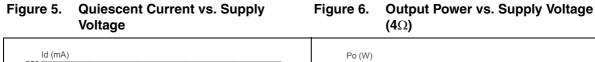
Table 3. Electrical Characteristics (continued)

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		(*******)				
Symbol	Parameter Test Condition			Тур.	Max.	Unit
I _{NLH}	Normal load current detection	V _O < (V _S - 5)pk IB2 (D7) = 0	500			mA
I _{NLL}	Normal load current detection	V _O < (V _S - 5)pk IB2 (D7) = 1	250			mA
I _{OLH}	Open load current detection	V _O < (V _S - 5)pk IB2 (D7) = 0			250	mA
I _{OLL}	Open load current detection	V _O < (V _S - 5)pk IB2 (D7) =1			125	mA
I ² C BUS INTERFACE						
S _{CL}	Clock Frequency				400	KHz
V _{IL}	Input Low Voltage				1.5	V
V _{IH}	Input High Voltage		2.3			V

 Table 3.
 Electrical Characteristics (continued)

3.4 Electrical characteristics curves



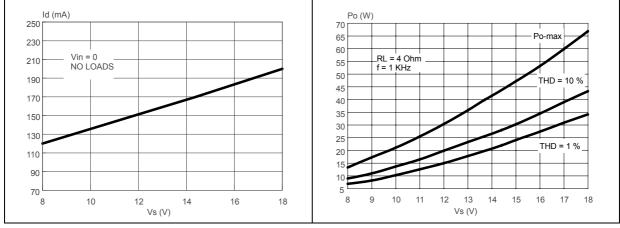
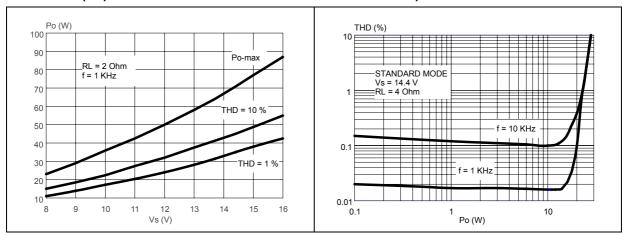


Figure 7. Output Power vs. Supply Voltage (2Ω)

Figure 8. Distortion vs. Output Power (4Ω, STD)



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Electrical specifications

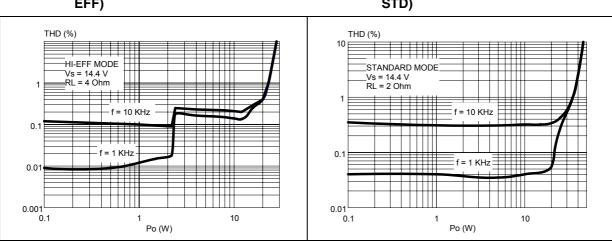
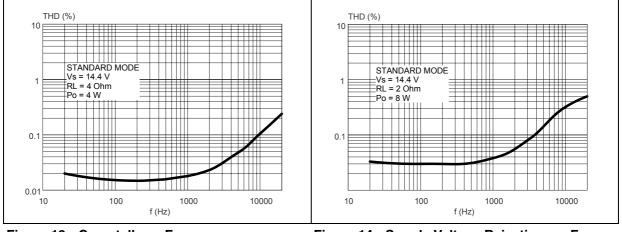


Figure 9.Distortion vs. Output Power (4Ω, HI-Figure 10.Distortion vs. Output Power (2Ω,EFF)STD)

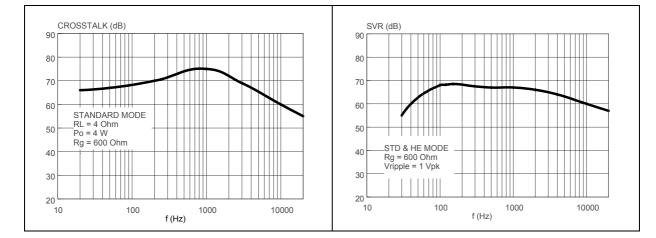


Figure 12. Distortion vs. Frequency (2 Ω)









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n (%)

n

Ptot

10

90

80

70

60

50

40

30

20

10

0

Figure 15. Power Dissipation & Efficiency vs. Output Power (4Ω, STD, SINE)

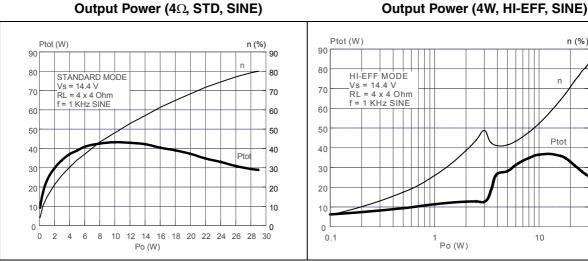
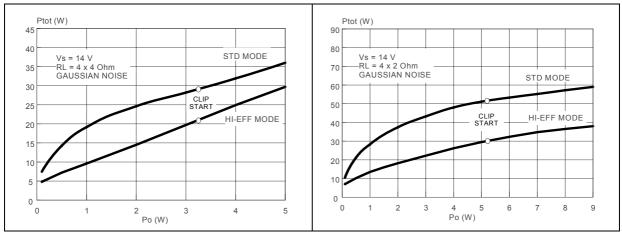


Figure 17. Power Dissipation vs. Average **Ouput Power (Audio Program** Simulation, 4Ω)

Figure 18. Power Dissipation vs. Average **Ouput Power (Audio Program** Simulation, 2Ω)

Figure 16. Power Dissipation & Efficiency vs.





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4 Diagnostics functional description

4.1 Turn-on diagnostic

It is activated at the turn-on (stand-by out) under I²Cbus request. Detectable output faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER
- OPEN SPEAKER

To verify if any of the above misconnections are in place, a subsonic (inaudible) current pulse (fig. 19) is internally generated, sent through the speaker(s) and sunk back. The Turn On diagnostic status is internally stored until a successive diagnostic pulse is requested (after a I^2C reading).

If the "stand-by out" and "diag. enable" commands are both given through a single programming step, the pulse takes place first (power stage still in stand-by mode, low, outputs= high impedance).

Afterwards, when the Amplifier is biased, the PERMANENT diagnostic takes place. The previous Turn On state is kept until a short appears at the outputs.

Figure 19. Turn - On diagnostic: working principle

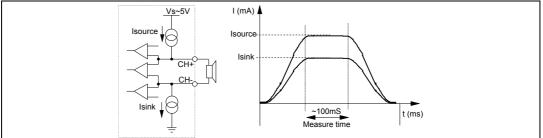
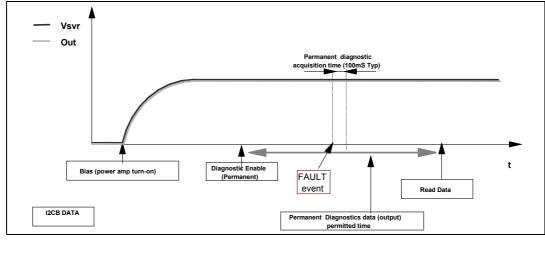


Figure 20 and *21* show SVR and OUTPUT waveforms at the turn-on (stand-by out) with and without turn-on diagnostic.

Figure 20. SVR and Output behaviour (Case 1: without turn-on diagnostic)



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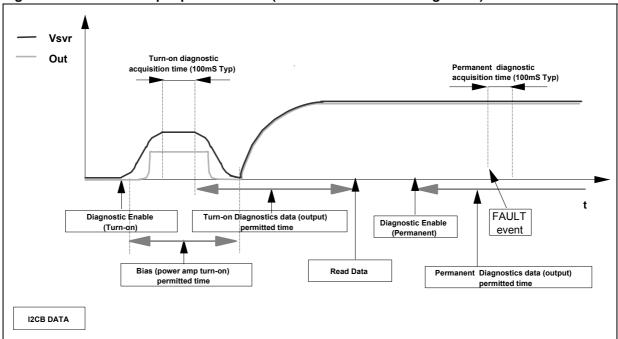
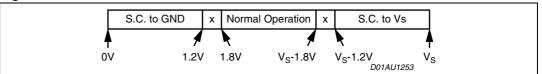


Figure 21. SVR and Output pin behaviour (CASE 2: with turn-on diagnostic)

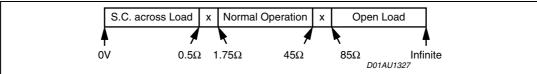
The information related to the outputs status is read and memorized at the end of the current pulse top. The acquisition time is 100 ms (typ.). No audible noise is generated in the process. As for SHORT TO GND / Vs the fault-detection thresholds remain unchanged from 26 dB to 12 dB gain setting. They are as follows:

Figure 22.



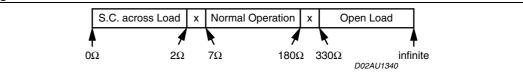
Concerning SHORT ACROSS THE SPEAKER / OPEN SPEAKER, the threshold varies from 26 dB to 12 dB gain setting, since different loads are expected (either normal speaker's impedance or high impedance). The values in case of 26 dB gain are as follows:

Figure 23.



If the Line-Driver mode (Gv= 12 dB and Line Driver Mode diagnostic = 1) is selected, the same thresholds will change as follows:

Figure 24.





4.2 **Permanent diagnostics**

Detectable conventional faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER

The following additional features are provided:

- OUTPUT OFFSET DETECTION

The TDA7564B has 2 operating statuses:

- 1. RESTART mode. The diagnostic is not enabled. Each audio channel operates independently from each other. If any of the a.m. faults occurs, only the channel(s) interested is shut down. A check of the output status is made every 1 ms (*Figure 25*). Restart takes place when the overload is removed.
- DIAGNOSTIC mode. It is enabled via I²C bus and self activates if an output overload (such to cause the intervention of the short-circuit protection) occurs to the speakers outputs. Once activated, the diagnostics procedure develops as follows (*Figure 26*):
 - To avoid momentary re-circulation spikes from giving erroneous diagnostics, a check of the output status is made after 1ms: if normal situation (no overloads) is detected, the diagnostic is not performed and the channel returns back active.
 - Instead, if an overload is detected during the check after 1 ms, then a diagnostic cycle having a duration of about 100 ms is started.
 - After a diagnostic cycle, the audio channel interested by the fault is switched to RESTART mode. The relevant data are stored inside the device and can be read by the microprocessor. When one cycle has terminated, the next one is activated by an I²C reading. This is to ensure continuous diagnostics throughout the carradio operating time.
 - To check the status of the device a sampling system is needed. The timing is chosen at microprocessor level (over half a second is recommended).

Figure 25. Restart timing without Diagnostic Enable (Permanent) - Each 1mS time, a sampling of the fault is done

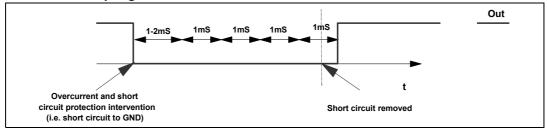
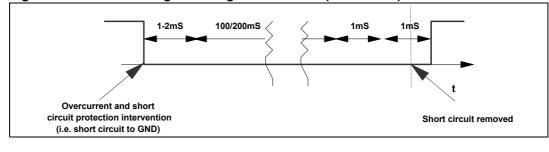


Figure 26. Restart timing with Diagnostic Enable (Permanent)



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4.3 Output DC offset detection

Any DC output offset exceeding ± 2 V are signalled out. This inconvenient might occur as a consequence of initially defective or aged and worn-out input capacitors feeding a DC component to the inputs, so putting the speakers at risk of overheating.

This diagnostic has to be performed with low-level output AC signal (or Vin = 0).

The test is run with selectable time duration by microprocessor (from a "start" to a "stop" command):

- START = Last reading operation or setting IB1 D5 (OFFSET enable) to 1
- STOP = Actual reading operation

Excess offset is signalled out if persistent throughout the assigned testing time. This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.

4.4 AC diagnostic

It is targeted at detecting accidental disconnection of tweeters in 2-way speaker and, more in general, presence of capacitively (AC) coupled loads.

This diagnostic is based on the notion that the overall speaker's impedance (woofer + parallel tweeter) will tend to increase towards high frequencies if the tweeter gets disconnected, because the remaining speaker (woofer) would be out of its operating range (high impedance). The diagnostic decision is made according to peak output current thresholds, and it is enabled by setting (IB2-D2) = 1. Two different detection levels are available:

HIGH CURRENT THRESHOLD IB2 (D7) = 0

lout > 500mApk = NORMAL STATUS

lout < 250mApk = OPEN TWEETER

LOW CURRENT THRESHOLD IB2 (D7) = 1

lout > 250mApk = NORMAL STATUS

lout < 125mApk = OPEN TWEETER

To correctly implement this feature, it is necessary to briefly provide a signal tone (with the amplifier in "play") whose frequency and magnitude are such to determine an output current higher than 500mApk with IB2(D7)=0 (higher than 250mApk with IB2(D7)=1) in normal conditions and lower than 250mApk with IB2(D7)=0 (lower than 125mApk with IB2(D7)=1) should the parallel tweeter be missing.

The test has to last for a minimum number of 3 sine cycles starting from the activation of the AC diagnostic function IB2<D2>) up to the I^2C reading of the results (measuring period). To confirm presence of tweeter, it is necessary to find at least 3 current pulses over the above threholds over all the measuring period, else an "open tweeter" message will be issued.

The frequency / magnitude setting of the test tone depends on the impedance characteristics of each specific speaker being used, with or without the tweeter connected (to be calculated case by case). High-frequency tones (> 10 KHz) or even ultrasonic signals are recommended for their negligible acoustic impact and also to maximize the impedance module's ratio between with tweeter-on and tweeter-off.



Diagnostics functional description

Figure 27 shows the Load Impedance as a function of the peak output voltage and the relevant diagnostic fields.

This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.

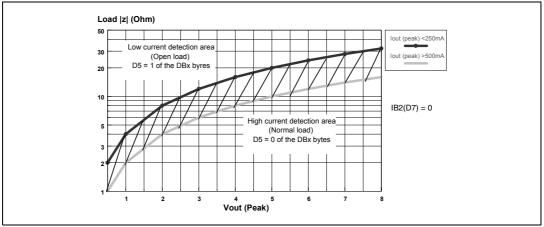
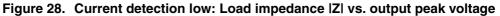
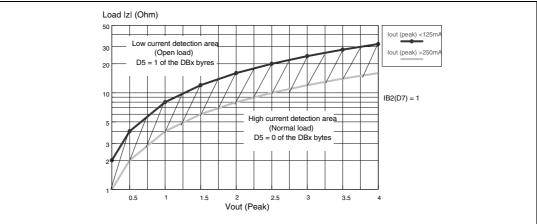


Figure 27. Current detection high: Load impedance |Z| vs. output peak voltage





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5 Multiple faults

When more misconnections are simultaneously in place at the audio outputs, it is guaranteed that at least one of them is initially read out. The others are notified after successive cycles of I²C reading and faults removal, provided that the diagnostic is enabled. This is true for both kinds of diagnostic (Turn on and Permanent).

The table below shows all the couples of double-fault possible. It should be taken into account that a short circuit with the 4 ohm speaker unconnected is considered as double fault.

	S. GND (so)	S. GND (sk)	S. Vs	S. Across L.	Open L.				
S. GND (so)	S. GND	S. GND	S. Vs + S. GND	S. GND	S. GND				
S. GND (sk)	/	S. GND	S. Vs	S. GND	Open L. (*)				
S. Vs	/	/	S. Vs	S. Vs	S. Vs				
S. Across L.	/	/	/	S. Across L.	N.A.				
Open L.	/	/	/	/	Open L. (*)				

 Table 4.
 Double fault table for Turn On Diagnostic

S. GND (so) / S. GND (sk) in the above table make a distinction according to which of the 2 outputs is shorted to ground (test-current source side= so, test-current sink side = sk). More precisely, in Channels LF and RR, so = CH+, sk = CH-; in Channels LR and RF, so = CH-, sk = CH+.

In Permanent Diagnostic the table is the same, with only a difference concerning Open Load(*), which is not among the recognisable faults. Should an Open Load be present during the device's normal working, it would be detected at a subsequent Turn on Diagnostic cycle (i.e. at the successive Car Radio Turn on).

5.1 Faults availability

All the results coming from l²Cbus, by read operations, are the consequence of measurements inside a defined period of time. If the fault is stable throughout the whole period, it will be sent out.

To guarantee always resident functions, every kind of diagnostic cycles (Turn on, Permanent, Offset) will be reactivate after any I^2C reading operation. So, when the micro reads the I^2C , a new cycle will be able to start, but the read data will come from the previous diag. cycle (i.e. The device is in Turn On state, with a short to Gnd, then the short is removed and micro reads I^2C . The short to Gnd is still present in bytes, because it is the result of the previous cycle. If another I^2C reading operation occurs, the bytes do not show the short). In general to observe a change in Diagnostic bytes, two I^2C reading operations are necessary.



6 Thermal protection

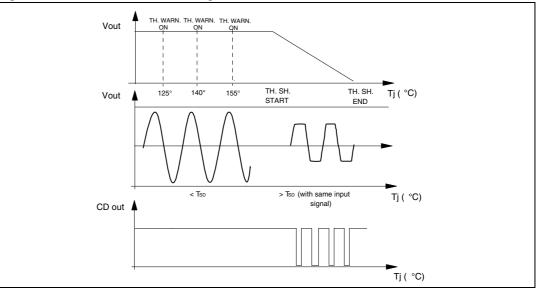
Thermal protection is implemented through thermal foldback (Figure 29).

Thermal foldback begins limiting the audio input to the amplifier stage as the junction temperatures rise above the normal operating range. This effectively limits the output power capability of the device thus reducing the temperature to acceptable levels without totally interrupting the operation of the device.

The output power will decrease to the point at which thermal equilibrium is reached. Thermal equilibrium will be reached when the reduction in output power reduces the dissipated power such that the die temperature falls below the thermal foldback threshold. Should the device cool, the audio level will increase until a new thermal equilibrium is reached or the amplifier reaches full power. Thermal foldback will reduce the audio output level in a linear manner.

Three Thermal warning are available through the I²C bus data.

Figure 29. Thermal Foldback Diagram



6.1 I²C programming/reading sequences

A correct turn on/off sequence respectful of the diagnostic timings and producing no audible noises could be as follows (after battery connection):

TURN-ON: (STAND-BY OUT + DIAG ENABLE) --- 500 ms (min) --- MUTING OUT

TURN-OFF: MUTING IN --- 20 ms --- (DIAG DISABLE + STAND-BY IN) Car Radio Installation: DIAG ENABLE (write) --- 200 ms --- I²C read (repeat until All faults disappear).

AC TEST: FEED H.F. TONE -- AC DIAG ENABLE (write) --- WAIT > 3 CYCLES --- I^2C read (repeat I^2C reading until tweeter-off message disappears).

OFFSET TEST: Device in Play (no signal) -- OFFSET ENABLE - 30ms - I²C reading (repeat I²C reading until high-offset message disappears).

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7 Fast muting

The muting time can be shortened to less than 1.5ms by setting (IB2) D5 = 1. This option can be useful in transient battery situations (i.e. during car engine cranking) to quickly turnoff the amplifier for avoiding any audible effects caused by noise/transients being injected by preamp stages. The bit must be set back to "0" shortly after the mute transition.



8 I²C Bus interface

Data transmission from microprocessor to the TDA7564B and viceversa takes place through the 2 wires I^2C BUS interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

8.0.1 Data Validity

As shown by *Figure 30*, the data on the SDA line must be stable during the high period of the clock. The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

8.0.2 Start and Stop Conditions

As shown by *Figure 31* a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH. The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

8.0.3 Byte Format

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

8.0.4 Acknowledge

The transmitter* puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see *Figure 32*). The receiver** the acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDAline is stable LOW during this clock pulse.

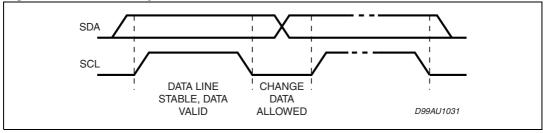
* Transmitter

- master (μ P) when it writes an address to the TDA7564B
- slave (TDA7564B) when the μ P reads a data byte from TDA7564B

** Receiver

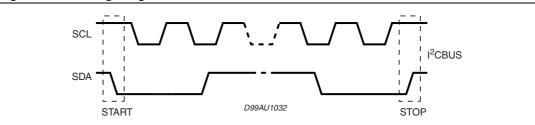
- slave (TDA7564B) when the μ P writes an address to the TDA7564B
- master (μP) when it reads a data byte from TDA7564B

Figure 30. Data Validity on the I²CBUS

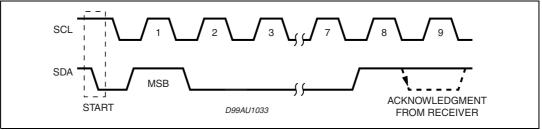


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All the functions of the TDA7564B are activated by I^2C interface.

The bit 0 of the "ADDRESS BYTE" defines if the next bytes are write instruction (from µP to TDA7564B) or read instruction (from TDA7564B to µP).

Table 5. **Chip Address:**

D7

D7						D0		
1	1	0	1	1	0	0	Х	D8 Hex

X = 0 Write to device

X = 1 Read from device

If R/W = 0, the μ P sends 2 "Instruction Bytes": IB1 and IB2.

Table 6. IB1

D7	0
D6	Diagnostic enable (D6 = 1) Diagnostic defeat (D6 = 0)
D5	Offset Detection enable (D5 = 1) Offset Detection defeat (D5 = 0)
D4	Front Channel Gain = $26dB (D4 = 0)$ Gain = $12dB (D4 = 1)$
D3	Rear Channel Gain = 26dB (D3 = 0) Gain = 12dB (D3 = 1)
D2	Mute front channels (D2 = 0) Unmute front channels (D2 = 1)
D1	Mute rear channels (D1 = 0) Unmute rear channels (D1 = 1)
D0	Clip detector 2% (D0 = 0) Clip detector 10% (D0 = 1)

Table 7. IB2

D7	current detection threshold High th (D7 = 0) Low th (D7 =1)	
D6	0	
D5	Normal muting time (D5 = 0) Fast muting time (D5 = 1)	
D4	Stand-by on - Amplifier not working - (D4 = 0) Stand-by off - Amplifier working - (D4 = 1)	



Table 7.	IB2 (continued)
D3	Power amplifier mode diagnostic (D3 = 0) Line driver mode diagnostic (D3 = 1)
D2	Current detection diagnostic enabled (D2 = 1) Current detection diagnostic defeat (D2 = 0)
D1	Right Channels Power amplifier working in standard mode (D1 = 0) Power amplifier working in high efficiency mode (D1 = 1)
D0	Left Channels Power amplifier working in standard mode ($D0 = 0$) Power amplifier working in high efficiency mode ($D0 = 1$)

Table 7. IB2 (continued)

If R/W = 1, the TDA7564B sends 4 "Diagnostics Bytes" to μ P: DB1, DB2, DB3 and DB4.

Table 8. DB1

D7	Thermal warning 1 active (D7 = 1) T=155 °C	
D6	Diag. cycle not activated or not terminated $(D6 = 0)$ Diag. cycle terminated $(D6 = 1)$	
D5	Channel LF current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel LF current detection IB2 (D7) = 1 Output peak current < 125 mA - Open load (D5 = 1) Output peak current > 250 mA - Normal load (D5 = 0)
D4	Channel LF Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)	
D3	Channel LF Normal load (D3 = 0) Short load (D3 = 1)	
D2	Channel LF Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Offset diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)	
D1	Channel LF No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)	
D0	Channel LF No short to GND (D1 = 0) Short to GND (D1 = 1)	



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Table 9	9. DB2				
D7	Offset detection not activated ($D7 = 0$) Offset detection activated ($D7 = 1$)				
D6	Current sensor not activated (D6 = 0) Current sensor activated (D6 = 1)				
D5	Channel LR current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel LR current detection IB2 (D7) = 1 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)			
D4	Channel LR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)				
D3	Channel LR Normal load (D3 = 0) Short load (D3 = 1)				
D2	Channel LR Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)				
D1	Channel LR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)				
D0	Channel LR No short to GND (D1 = 0) Short to GND (D1 = 1)				

Table 10. DB3

D7	Stand-by status (= IB1 - D4)					
D6	Diagnostic status (= IB1 - D6)					
D5	Channel RF current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel RF current detection IB2 (D7) = 1 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)				
D4	Channel RF Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)					
D3	Channel RF Normal load (D3 = 0) Short load (D3 = 1)					

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Table 10. DB3 (continued)

D7	Stand-by status (= IB1 - D4)
D2	Channel RF Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel RF No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel RF No short to GND (D1 = 0) Short to GND (D1 = 1)

Table 11. DB4

D7	Thermal warning 2 active (D7 =1) T=140°C					
D6	Thermal warning 3 active (D6 =1) T=125°C					
D5	Channel RR current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel RR current detection IB2 (D7) = 1 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)				
D4	Channel RR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)					
D3	Channel RR Normal load (D3 = 0) Short load (D3 = 1)					
D2	Channel RR Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)					
D1	Channel RR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)					
D0	Channel RR No short to GND (D1 = 0) Short to GND (D1 = 1)					



10 Examples of bytes sequence

1 - Turn-On diagnostic - Write operation

Start Address byte with D0 = 0	ACK	IB1 with D6 = 1	ACK	IB2	ACK	STOP
--------------------------------	-----	-----------------	-----	-----	-----	------

2 - Turn-On diagnostic - Read operation

Start Address byte with D0 = 1 ACK D	31 ACK DB2 ACK	DB3 ACK DB4 ACK	STOP
--------------------------------------	----------------	-----------------	------

The delay from 1 to 2 can be selected by software, starting from 1 ms

3a - Turn-On of the power amplifier with 26dB gain, mute on, diagnostic defeat, High eff. mode both channels.

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			X000000X		XXX1X011		

3b - Turn-Off of the power amplifier

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
		X0XXXXXX		XXX0XXXX			

4 - Offset detection procedure enable

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			XX1XX11X		XXX1X0XX		

5 - Offset detection procedure stop and reading operation (the results are valid only for the offset detection bits (D2 of the bytes DB1, DB2, DB3, DB4)

Start Address byte with D0 = 1 ACK DB1 ACK DB2 ACK DB3 ACK DB4 AC	STOP
---	------

 The purpose of this test is to check if a D.C. offset (2V typ.) is present on the outputs, produced by input capacitor with anomalous leackage current or humidity between pins.

The delay from 4 to 5 can be selected by software, starting from 1ms

6 - Current detection procedure start (the AC inputs must be with a proper signal that depends on the type of load)

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			XX01111X		XXX1X1XX		

Current detection reading operation (the results valid only for the current sensor detection bits - D5 of the bytes DB1, DB2, DB3, DB4)

Start Address byte with	n D0 = 1 ACK	DB1	ACK	DB2	ACK	DB3	ACK	DB4	ACK	STOP
-------------------------	--------------	-----	-----	-----	-----	-----	-----	-----	-----	------

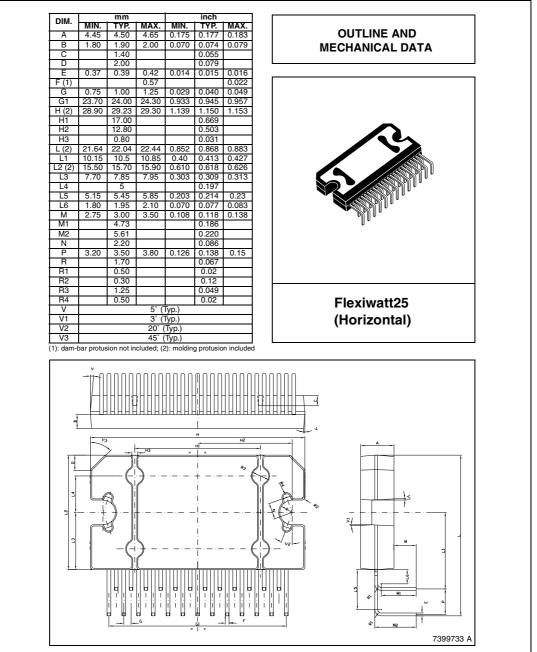
- During the test, a sinus wave with a proper amplitude and frequency (depending on the loudspeaker under test) must be present. The minimum number of periods that are needed to detect a normal load is 5.
- The delay from 6 to 7 can be selected by software, starting from 1ms.

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11 Package information

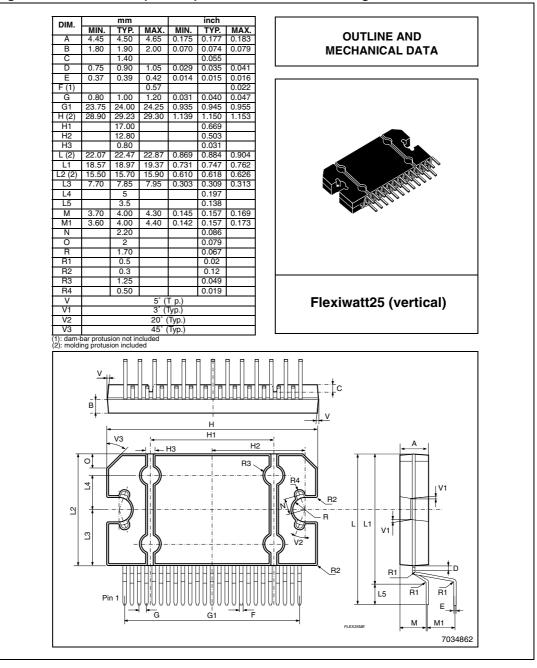
In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.





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12 Revision history

Table 12. Document revision history

Date	Revision	Changes
14-Sep-2006	1	Intial release.



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